



Material Content Data Sheet



Sales Product Name		IPS80R900P7		Issued		19. January 2018		
MA#		MA002116524						
Package		PG-TO251-3-344		Weight*		334.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.033	0.61	0.61	6076	6076
leadframe	inorganic material	phosphorus	7723-14-0	0.046	0.01		138	
	non noble metal	iron	7439-89-6	0.154	0.05		461	
	non noble metal	copper	7440-50-8	154.154	46.08	46.14	460678	461277
	non noble metal	aluminium	7429-90-5	0.470	0.14	0.14	1405	1405
wire	non noble metal	aluminium	7429-90-5	0.470	0.14	0.14	1405	1405
encapsulation	organic material	carbon black	1333-86-4	0.444	0.13		1326	
	plastics	epoxy resin	-	13.462	4.02		40231	
	inorganic material	silicondioxide	60676-86-0	134.030	40.05	44.20	400540	442097
leadfinish	non noble metal	tin	7440-31-5	4.142	1.24	1.24	12378	12378
plating	non noble metal	nickel	7440-02-0	0.607	0.18	0.18	1813	1813
solder	non noble metal	tin	7440-31-5	0.044	0.01		131	
	noble metal	silver	7440-22-4	0.055	0.02		163	
	non noble metal	lead	7439-92-1	2.086	0.62	0.65	6235	6529
heatspreader	inorganic material	phosphorus	7723-14-0	0.007	0.00		21	
	non noble metal	iron	7439-89-6	0.023	0.01		68	
	non noble metal	copper	7440-50-8	22.867	6.83	6.84	68336	68425
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com